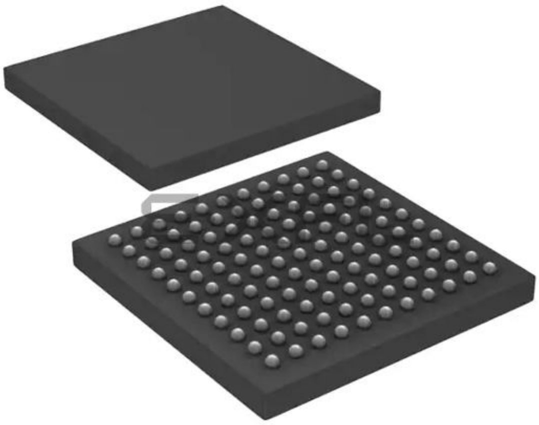


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	85
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj64ga310t-i-bg

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as V_{DD}, V_{SS}, AV_{DD} and AV_{SS}, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 μF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μF to 0.001 μF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 μF in parallel with 0.001 μF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including microcontrollers to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 μF to 47 μF.

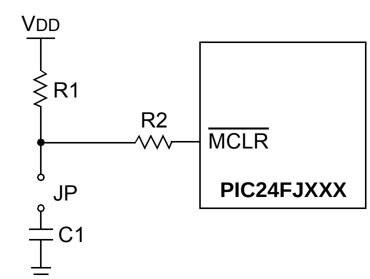
2.3 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions: device Reset, and device programming and debugging. If programming and debugging are not required in the end application, a direct connection to V_{DD} may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{\text{MCLR}}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin V_{IH} and V_{IL} specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin V_{IH} and V_{IL} specifications are met.

3.0 CPU

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to **"CPU with Extended Data Space (EDS)"** (DS39732) in the *"dsPIC33/PIC24 Family Reference Manual"*. The information in this data sheet supersedes the information in the FRM.

The PIC24F CPU has a 16-bit (data) modified Harvard architecture with an enhanced instruction set and a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M instructions of user program memory space. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `REPEAT` instructions, which are interruptible at any point.

PIC24F devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can act as a data, address or address offset register. The 16^{th} Working register (W15) operates as a Software Stack Pointer for interrupts and calls.

The lower 32 Kbytes of the Data Space can be accessed linearly. The upper 32 Kbytes of the Data Space are referred to as Extended Data Space (EDS) to which the extended data RAM, EPMP memory space or program memory can be mapped.

The Instruction Set Architecture (ISA) has been significantly enhanced beyond that of the PIC18, but maintains an acceptable level of backward compatibility. All PIC18 instructions and addressing modes are supported, either directly, or through simple macros. Many of the ISA enhancements have been driven by compiler efficiency needs.

The core supports Inherent (no operand), Relative, Literal and Memory Direct Addressing modes, along with three other groups of addressing modes. All modes support Register Direct and various Register Indirect modes. Each group offers up to seven addressing modes. Instructions are associated with predefined addressing modes depending upon their functional requirements.

For most instructions, the core is capable of executing a data (or program data) memory read, a Working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing trinary operations (that is, A + B = C) to be executed in a single cycle.

A high-speed, 17-bit x 17-bit multiplier has been included to significantly enhance the core arithmetic capability and throughput. The multiplier supports Signed, Unsigned and Mixed mode, 16-bit x 16-bit or 8-bit x 8-bit, integer multiplication. All multiply instructions execute in a single cycle.

The 16-bit ALU has been enhanced with integer divide assist hardware that supports an iterative non-restoring divide algorithm. It operates in conjunction with the `REPEAT` instruction looping mechanism and a selection of iterative divide instructions to support 32-bit (or 16-bit), divided by 16-bit, integer signed and unsigned division. All divide operations require 19 cycles to complete but are interruptible at any cycle boundary.

The PIC24F has a vectored exception scheme with up to 8 sources of non-maskable traps and up to 118 interrupt sources. Each interrupt source can be assigned to one of seven priority levels.

A block diagram of the CPU is shown in Figure 3-1.

3.1 Programmer's Model

The programmer's model for the PIC24F is shown in Figure 3-2. All registers in the programmer's model are memory-mapped and can be manipulated directly by instructions. A description of each register is provided in Table 3-1. All registers associated with the programmer's model are memory-mapped.

4.0 MEMORY ORGANIZATION

As Harvard architecture devices, PIC24F microcontrollers feature separate program and data memory spaces and buses. This architecture also allows direct access of program memory from the Data Space during code execution.

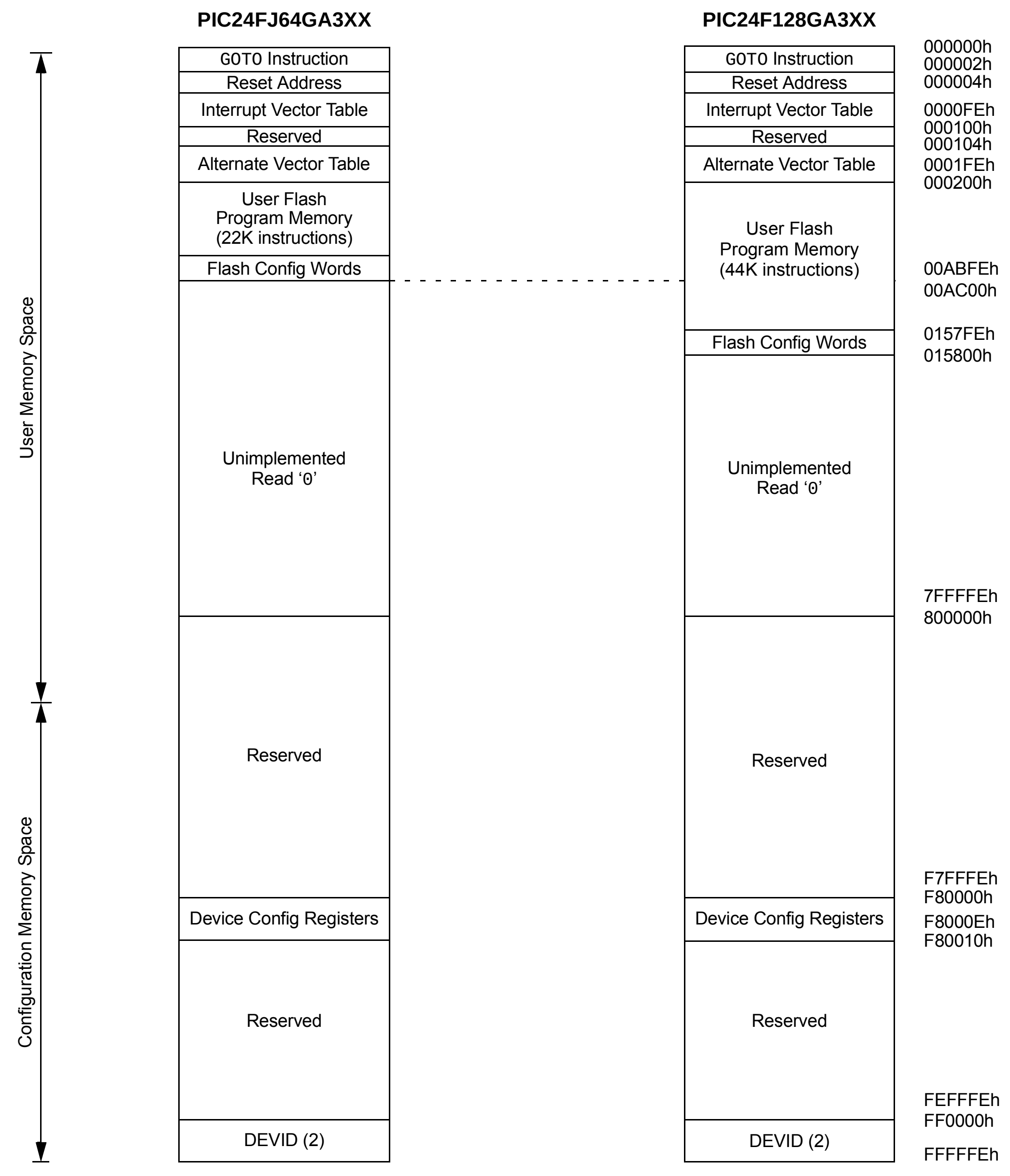
4.1 Program Memory Space

The program address memory space of the PIC24FJ128GA310 family devices is 4M instructions. The space is addressable by a 24-bit value derived from either the 23-bit Program Counter (PC) during program execution, or from table operation or Data Space remapping, as described in **Section 4.3 "Interfacing Program and Data Memory Spaces"**.

User access to the program memory space is restricted to the lower half of the address range (000000h to 7FFFFFh). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

Memory maps for the PIC24FJ128GA310 family of devices are shown in Figure 4-1.

FIGURE 4-1: PROGRAM SPACE MEMORY MAP FOR PIC24FJ128GA310 FAMILY DEVICES



Note: Memory areas are not shown to scale.

4.2 Data Memory Space

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to **"Data Memory with Extended Data Space (EDS)"** (DS39733) in the *"dsPIC33/PIC24 Family Reference Manual"*. The information in this data sheet supersedes the information in the FRM.

The PIC24F core has a 16-bit-wide data memory space, addressable as a single linear range. The Data Space is accessed using two Address Generation Units (AGUs), one each for read and write operations. The Data Space memory map is shown in Figure 4-3.

The 16-bit wide data addresses in the data memory space point to bytes within the Data Space (DS). This gives a DS address range of 64 Kbytes or 32K words. The lower half (0000h to 7FFFh) is used for implemented (on-chip) memory addresses.

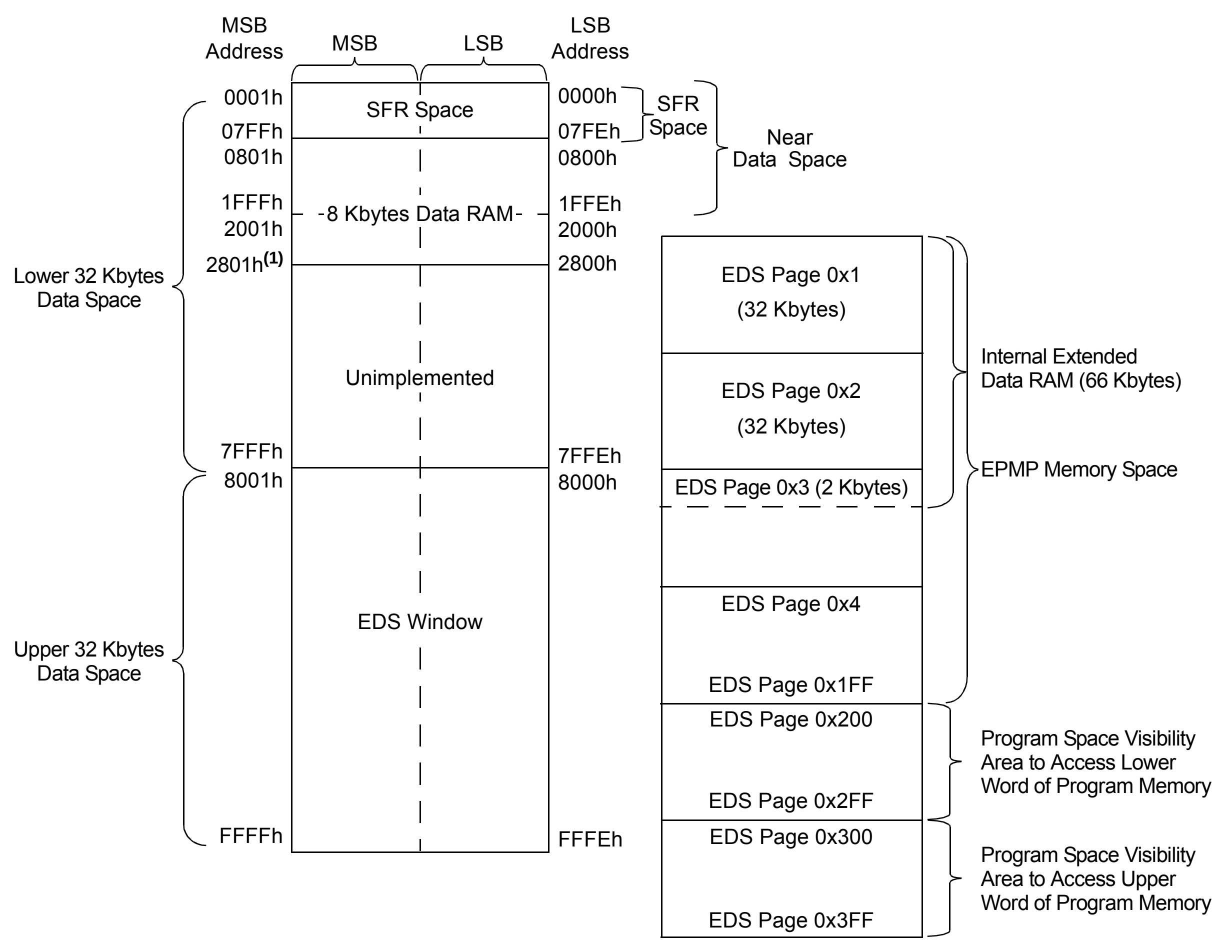
The upper half of data memory address space (8000h to FFFFh) is used as a window into the Extended Data Space (EDS). This allows the microcontroller to directly access a greater range of data beyond the standard 16-bit address range. EDS is discussed in detail in **Section 4.2.5 "Extended Data Space (EDS)"**.

The lower half of DS is compatible with previous PIC24F microcontrollers without EDS. All PIC24FJ128GA310 family devices implement 8 Kbytes of data RAM in the lower half of DS, from 0800h to 27FFh.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all Data Space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

FIGURE 4-3: DATA SPACE MEMORY MAP FOR PIC24FJ128GA310 FAMILY DEVICES



Note: Memory areas not shown to scale.

REGISTER 7-1: RCON: RESET CONTROL REGISTER

R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
TRAPR[(1)]	IOPUWR[(1)]	—	RETEN[(2)]	—	DPSLP[(1)]	CM[(1)]	VREGS[(3)]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR[(1)]	SWR[(1)]	SWDTEN[(4)]	WDTO[(1)]	SLEEP[(1)]	IDLE[(1)]	BOR[(1)]	POR[(1)]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit[(1)]
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit[(1)]
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register is used as an Address Pointer and caused a Reset
0 = An illegal opcode or Uninitialized W Reset has not occurred

bit 13 **Unimplemented:** Read as '0'

bit 12 **RETEN:** Retention Mode Enable bit[(2)]
1 = Retention mode is enabled while device is in Sleep modes (1.2V regulator supplies to the core)
0 = Retention mode is disabled; normal voltage levels are present

bit 11 **Unimplemented:** Read as '0'

bit 10 **DPSLP:** Deep Sleep Flag bit[(1)]
1 = Device has been in Deep Sleep mode
0 = Device has not been in Deep Sleep mode

bit 9 **CM:** Configuration Word Mismatch Reset Flag bit[(1)]
1 = A Configuration Word Mismatch Reset has occurred
0 = A Configuration Word Mismatch Reset has not occurred

bit 8 **VREGS:** Program Memory Power During Sleep bit[(3)]
1 = Program memory bias voltage remains powered during Sleep
0 = Program memory bias voltage is powered down during Sleep

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit[(1)]
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit[(1)]
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the $\overline{\text{LPCFG}}$ Configuration bit is 1' (unprogrammed), the retention regulator is disabled and the RETEN bit has no effect.

3: Re-enabling the regulator after it enters Standby mode will add a delay, T_{VREG}, when waking up from Sleep. Applications that do not use the voltage regulator should set this bit to prevent this delay from occurring.

4: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled**,** regardless of the SWDTEN bit setting.

REGISTER 8-13: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPF1IE	T3IE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14 **DMA1IE:** DMA Channel 1 Interrupt Flag Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 13 **AD1IE:** ADC1 Conversion Complete Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 12 **U1TXIE:** UART1 Transmitter Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 11 **U1RXIE:** UART1 Receiver Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 10 **SPI1IE:** SPI1 Transfer Complete Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 9 **SPF1IE:** SPI1 Fault Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 8 **T3IE:** Timer3 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 7 **T2IE:** Timer2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 6 **OC2IE:** Output Compare Channel 2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 5 **IC2IE:** Input Capture Channel 2 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 4 **DMA0IE:** DMA Channel 0 Interrupt Flag Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 3 **T1IE:** Timer1 Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-21: IPC0: INTERRUPT PRIORITY CONTROL REGISTER 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T1IP2	T1IP1	T1IP0	—	OC1IP2	OC1IP1	OC1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC1IP2	IC1IP1	IC1IP0	—	INT0IP2	INT0IP1	INT0IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T1IP<2:0>:** Timer1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OC1IP<2:0>:** Output Compare Channel 1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **IC1IP<2:0>:** Input Capture Channel 1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **INT0IP<2:0>:** External Interrupt 0 Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-35: IPC15: INTERRUPT PRIORITY CONTROL REGISTER 15

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	RTCIP2	RTCIP1	RTCIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	DMA5IP2	DMA5IP1	DMA5IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **RTCIP<2:0>:** Real-Time Clock and Calendar Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **DMA5IP<2:0>:** DMA Channel 5 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

10.4.2 EXITING DEEP SLEEP MODES

Deep Sleep modes exit on any one of the following events:

- POR event on VDD supply. If there is no DSBOR circuit to re-arm the VDD supply POR circuit, the external VDD supply must be lowered to the natural arming voltage of the POR circuit.
- DSWDT time-out. When the DSWDT timer times out, the device exits Deep Sleep.
- RTCC alarm (if RTCEN = `1`).
- Assertion (‘`0`’) of the $\overline{\text{MCLR}}$ pin.
- Assertion of the INT0 pin (if the interrupt was enabled before Deep Sleep mode was entered). The polarity configuration is used to determine the assertion level (‘`0`’ or ‘`1`’) of the pin that will cause an exit from Deep Sleep mode. Exiting from Deep Sleep mode requires a change on the INT0 pin while in Deep Sleep mode.

Note:	Any interrupt pending, when entering Deep Sleep mode, is cleared.

Exiting Deep Sleep generally does not retain the state of the device and is equivalent to a Power-on Reset (POR) of the device. Exceptions to this include the RTCC (if present), which remains operational through the wake-up, the DSGPRx registers and DSWDT.

Wake-up events that occur from the time Deep Sleep exits, until the time the POR sequence completes, are not ignored. The DSWAKE register will capture ALL wake-up events, from DSEN set to RELEASE clear.

The sequence for exiting Deep Sleep mode is:

1. After a wake-up event, the device exits Deep Sleep and performs a POR. The DSEN bit is cleared automatically. Code execution resumes at the Reset vector.
2. To determine if the device exited Deep Sleep, read the Deep Sleep bit, DPSLP (RCON<10>). This bit will be set if there was an exit from Deep Sleep mode. If the bit is set, clear it.
3. Determine the wake-up source by reading the DSWAKE register.
4. Determine if a DSBOR event occurred during Deep Sleep mode by reading the DSBOR bit (DSCON<1>).
5. If application context data has been saved, read it back from the DSGPR0 and DSGPR1 registers.
6. Clear the RELEASE bit (DSCON<0>).

10.4.3 SAVING CONTEXT DATA WITH THE DSGPRx REGISTERS

As exiting Deep Sleep mode causes a POR, most Special Function Registers reset to their default POR values. In addition, because VCORE power is not supplied in Deep Sleep mode, information in data RAM may be lost when exiting this mode.

Applications which require critical data to be saved prior to Deep Sleep may use the Deep Sleep General Purpose registers, DSGPR0 and DSGPR1, or data EEPROM (if available). Unlike other SFRs, the contents of these registers are preserved while the device is in Deep Sleep mode. After exiting Deep Sleep, software can restore the data by reading the registers and clearing the RELEASE bit (DSCON<0>).

10.4.4 I/O PINS IN DEEP SLEEP MODES

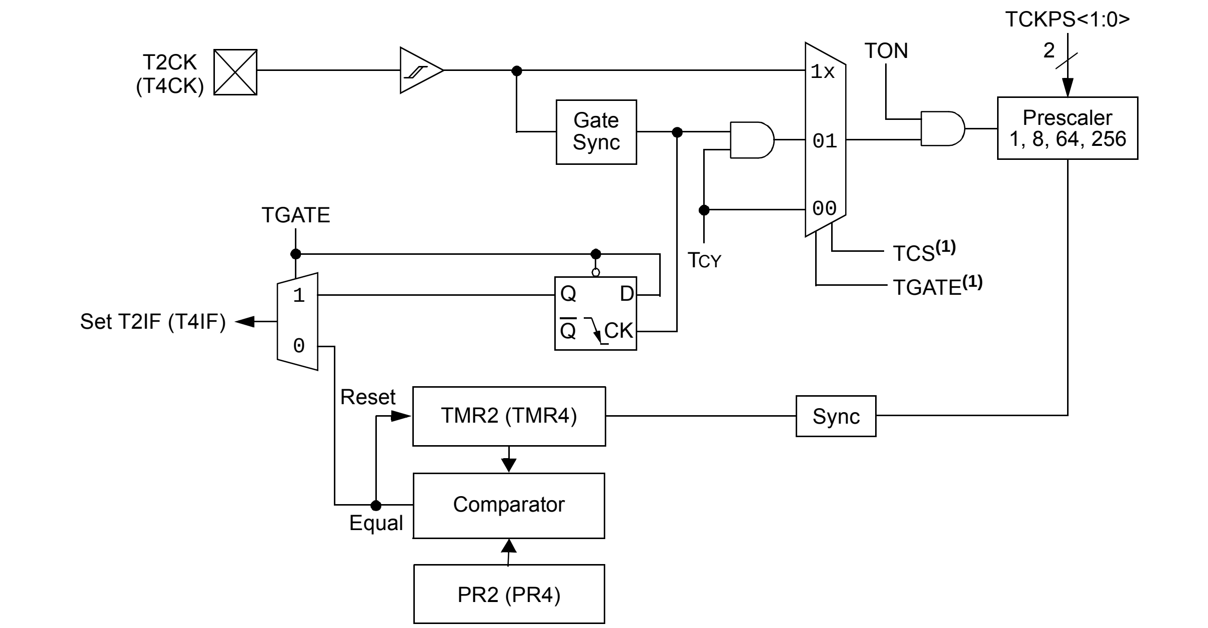
During Deep Sleep, the general purpose I/O pins retain their previous states and the Secondary Oscillator (SOSC) will remain running, if enabled. Pins that are configured as inputs (TRISx bit set), prior to entry into Deep Sleep, remain high-impedance during Deep Sleep. Pins that are configured as outputs (TRISx bit clear), prior to entry into Deep Sleep, remain as output pins during Deep Sleep. While in this mode, they continue to drive the output level determined by their corresponding LATx bit at the time of entry into Deep Sleep.

Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance, and pins configured as outputs continue to drive their previous value. After waking up, the TRISx and LATx registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/Os will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>), the I/O pins are “released”. This causes the I/O pins to take the states configured by their respective TRISx and LATx bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

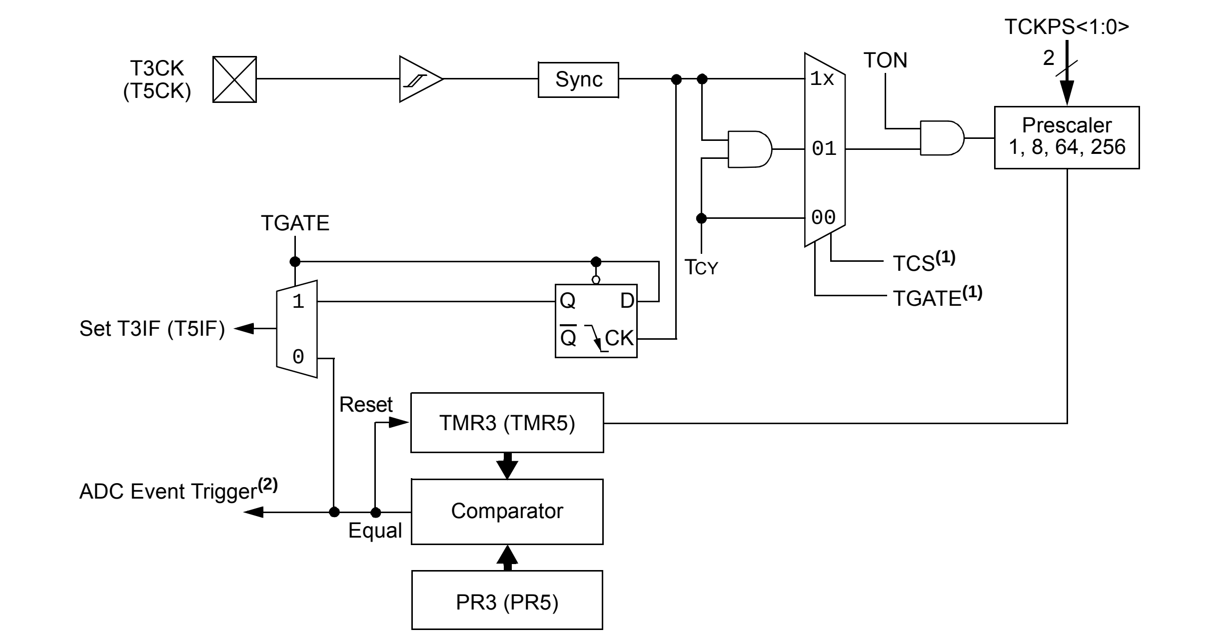
If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released, similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

FIGURE 13-2: TIMER2 AND TIMER4 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM



Note 1: The timer clock input must be assigned to an available RPn/RPIn pin before use. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

FIGURE 13-3: TIMER3 AND TIMER5 (16-BIT SYNCHRONOUS) BLOCK DIAGRAM



Note 1: The timer clock input must be assigned to an available RPn/RPIn pin before use. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

2: The ADC event trigger is available only on Timer3.

REGISTER 17-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I^{2}C™ pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I^{2}C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/$\overline{W}$ (i.e., software may write '0' to initiate stretch and write '1' to release clock). Hardware is clear at the beginning of slave transmission. Hardware is clear at the end of slave reception.
If STREN = 0:
Bit is R/S (i.e., software may only write '1' to release clock). Hardware is clear at the beginning of slave transmission.

bit 11 **IPMIEN:** Intelligent Platform Management Interface (IPMI) Enable bit
1 = IPMI Support mode is enabled; all addresses are Acknowledged
0 = IPMI mode is disabled

bit 10 **A10M:** 10-Bit Slave Addressing bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specifications
0 = Disables the SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I^{2}C slave)
1 = Enables interrupt when a general call address is received in the I2CxRSR (module is enabled for reception)
0 = General call address is disabled

bit 6 **STREN:** SCLx Clock Stretch Enable bit (when operating as I^{2}C slave)
Used in conjunction with the SCLREL bit.
1 = Enables software or receive clock stretching
0 = Disables software or receive clock stretching

REGISTER 21-6: LCDREF: LCD REFERENCE LADDER CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
LCDIRE	—	LCDCST2	LCDCST1	LCDCST0	VLCD3PE(1)	VLCD2PE(1)	VLCD1PE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
LRLAP1	LRLAP0	LRLBP1	LRLBP0	—	LRLAT2	LRLAT1	LRLAT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **LCDIRE**: LCD Internal Reference Enable bit
1 = Internal LCD reference is enabled and connected to the internal contrast control circuit
0 = Internal LCD reference is disabled

bit 14 **Unimplemented**: Read as '0'

bit 13-11 **LCDCST<2:0>**: LCD Contrast Control bits
Selects the resistance of the LCD contrast control resistor ladder:
111 = Resistor ladder is at maximum resistance (minimum contrast)
110 = Resistor ladder is at 6/7th of maximum resistance
101 = Resistor ladder is at 5/7th of maximum resistance
100 = Resistor ladder is at 4/7th of maximum resistance
011 = Resistor ladder is at 3/7th of maximum resistance
010 = Resistor ladder is at 2/7th of maximum resistance
001 = Resistor ladder is at 1/7th of maximum resistance
000 = Minimum resistance (maximum contrast); resistor ladder is shorted

bit 10 **VLCD3PE**: Bias 3 Pin Enable bit(1)
1 = Bias 3 level is connected to the external pin, LCDBIAS3
0 = Bias 3 level is internal (internal resistor ladder)

bit 9 **VLCD2PE**: Bias 2 Pin Enable bit(1)
1 = Bias 2 level is connected to the external pin, LCDBIAS2
0 = Bias 2 level is internal (internal resistor ladder)

bit 8 **VLCD1PE**: Bias 1 Pin Enable bit(1)
1 = Bias 1 level is connected to the external pin, LCDBIAS1
0 = Bias 1 level is internal (internal resistor ladder)

bit 7-6 **LRLAP<1:0>**: LCD Reference Ladder A Time Power Control bits
During Time Interval A:
11 = Internal LCD reference ladder is powered in High-Power mode
10 = Internal LCD reference ladder is powered in Medium Power mode
01 = Internal LCD reference ladder is powered in Low-Power mode
00 = Internal LCD reference ladder is powered down and unconnected

bit 5-4 **LRLBP<1:0>**: LCD Reference Ladder B Time Power Control bits
During Time Interval B:
11 = Internal LCD reference ladder is powered in High-Power mode
10 = Internal LCD reference ladder is powered in Medium Power mode
01 = Internal LCD reference ladder is powered in Low-Power mode
00 = Internal LCD reference ladder is powered down and unconnected

bit 3 **Unimplemented**: Read as '0'

Note 1: When using the external resistor ladder biasing, the LCDBIASx pins should be made analog and the respective TRISx bits should be set as inputs.

REGISTER 22-11: RTCCSWT: POWER CONTROL AND SAMPLE WINDOW TIMER REGISTER[1]

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
PWCSTAB7	PWCSTAB6	PWCSTAB5	PWCSTAB4	PWCSTAB3	PWCSTAB2	PWCSTAB1	PWCSTAB0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
PWCSAMP7[2]	PWCSAMP6[2]	PWCSAMP5[2]	PWCSAMP4[2]	PWCSAMP3[2]	PWCSAMP2[2]	PWCSAMP1[2]	PWCSAMP0[2]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **PWCSTAB<7:0>:** Power Control Stability Window Timer bits

`11111111` = Stability Window is 255 TPWCCLK clock periods
`11111110` = Stability Window is 254 TPWCCLK clock periods
...
`00000001` = Stability Window is 1 TPWCCLK clock period
`00000000` = No Stability Window; Sample Window starts when the alarm event triggers

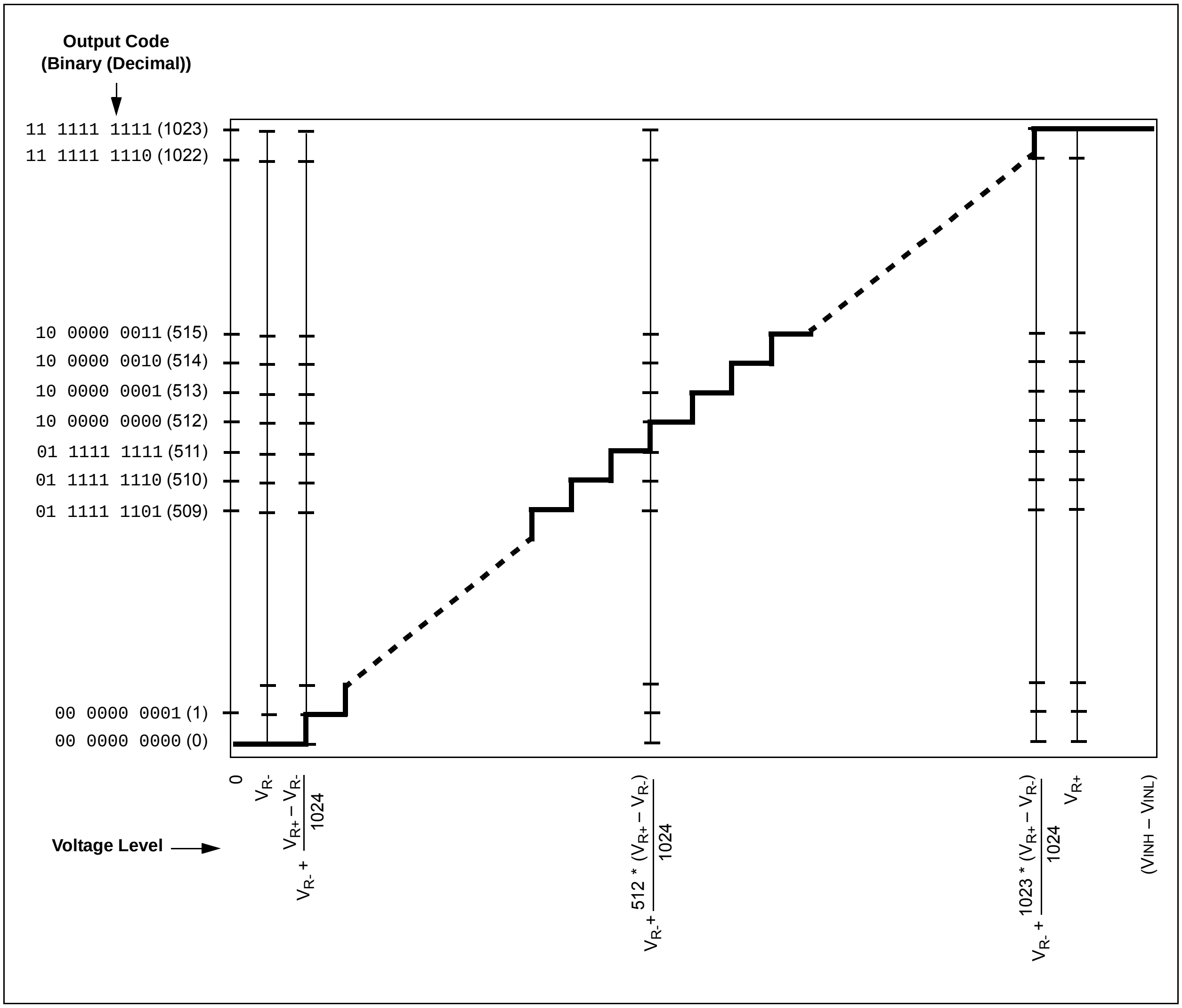
bit 7-0 **PWCSAMP<7:0>:** Power Control Sample Window Timer bits[2]

`11111111` = Sample Window is always enabled, even when PWCEN = `0`
`11111110` = Sample Window is 254 TPWCCLK clock periods
...
`00000001` = Sample Window is 1 TPWCCLK clock period
`00000000` = No Sample Window

Note 1: A write to this register is only allowed when RTCWREN = `1`.

2: The Sample Window always starts when the Stability Window timer expires, except when its initial value is 00h.

FIGURE 24-5: 10-BIT ADC TRANSFER FUNCTION



25.0 TRIPLE COMPARATOR MODULE

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to **"Scalable Comparator Module"** (DS39734) in the *"dsPIC33/PIC24 Family Reference Manual*". The information in this data sheet supersedes the information in the FRM.

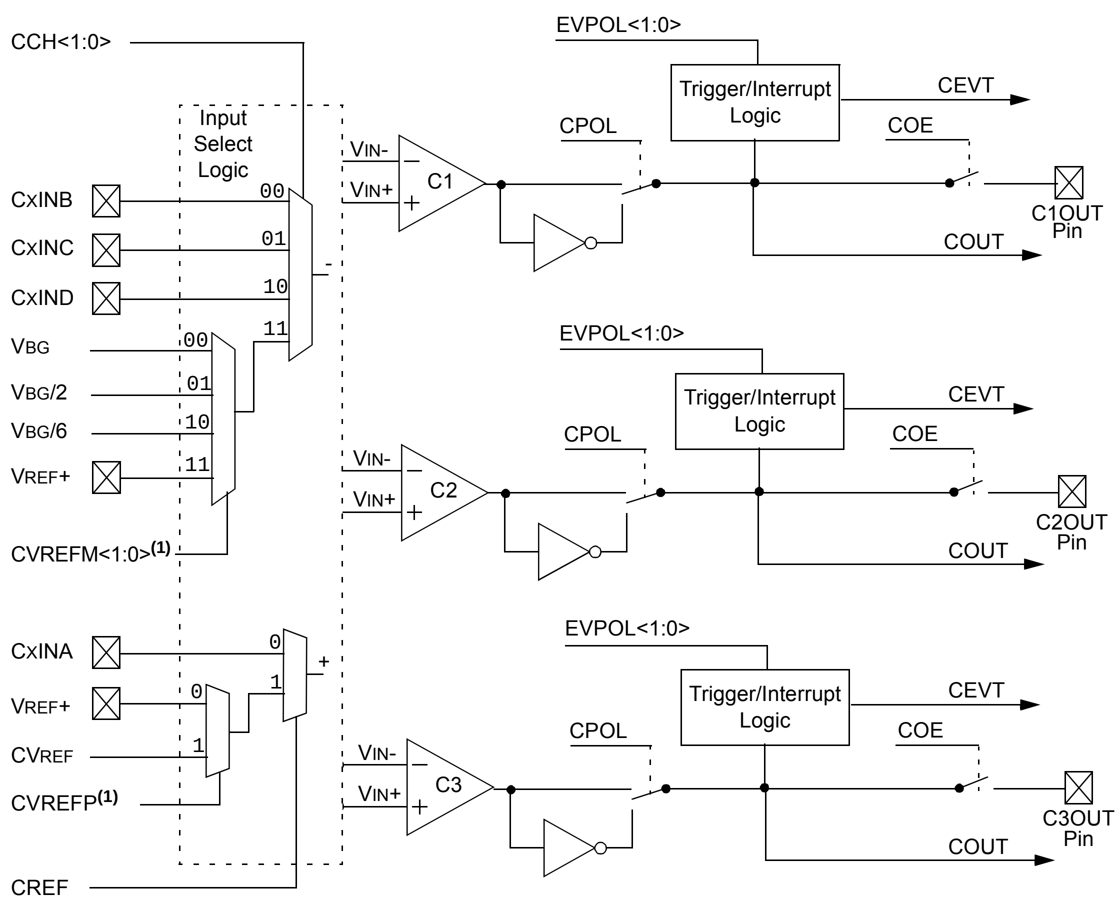
The triple comparator module provides three dual input comparators. The inputs to the comparator can be configured to use any one of five external analog inputs (CxINA, CxINB, CxINC, CxIND and VREF+) and a voltage reference input from one of the internal band gap references or the comparator voltage reference generator (VBG, VBG/2, VBG/6 and CVREF).

The comparator outputs may be directly connected to the CxOUT pins. When the respective COE equals '1', the I/O pad logic makes the unsynchronized output of the comparator available on the pin.

A simplified block diagram of the module in shown in Figure 25-1. Diagrams of the possible individual comparator configurations are shown in Figure 25-2.

Each comparator has its own control register, CMxCON (Register 25-1), for enabling and configuring its operation. The output and event status of all three comparators is provided in the CMSTAT register (Register 25-2).

FIGURE 25-1: TRIPLE COMPARATOR MODULE BLOCK DIAGRAM



Note 1: Refer to the CVRCON register (Register 26-1) for bit details.

REGISTER 25-1: CMxCON: COMPARATOR x CONTROL REGISTERS (COMPARATORS 1 THROUGH 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0, HS	R-0, HSC
CEN	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0
bit 7							bit 0

Legend:	HS = Hardware Settable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CEN:** Comparator Enable bit
- 1 = Comparator is enabled
- 0 = Comparator is disabled

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is present on the CxOUT pin
- 0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
- 1 = Comparator output is inverted
- 0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator Event bit
- 1 = Comparator event that is defined by EVPOL<1:0> has occurred; subsequent triggers and interrupts are disabled until the bit is cleared
- 0 = Comparator event has not occurred

bit 8 **COUT:** Comparator Output bit

When CPOL = 0:
- 1 = $V_{IN+} > V_{IN-}$
- 0 = $V_{IN+} < V_{IN-}$

When CPOL = 1:
- 1 = $V_{IN+} < V_{IN-}$
- 0 = $V_{IN+} > V_{IN-}$

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
- 11 = Trigger/event/interrupt is generated on any change of the comparator output (while CEVT = 0)
- 10 = Trigger/event/interrupt is generated on transition of the comparator output:
  - If CPOL = 0 (non-inverted polarity):
    High-to-low transition only.
  - If CPOL = 1 (inverted polarity):
    Low-to-high transition only.
- 01 = Trigger/event/interrupt is generated on transition of comparator output:
  - If CPOL = 0 (non-inverted polarity):
    Low-to-high transition only.
  - If CPOL = 1 (inverted polarity):
    High-to-low transition only.
- 00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

REGISTER 29-4: CW4: FLASH CONFIGURATION WORD 4 (CONTINUED)

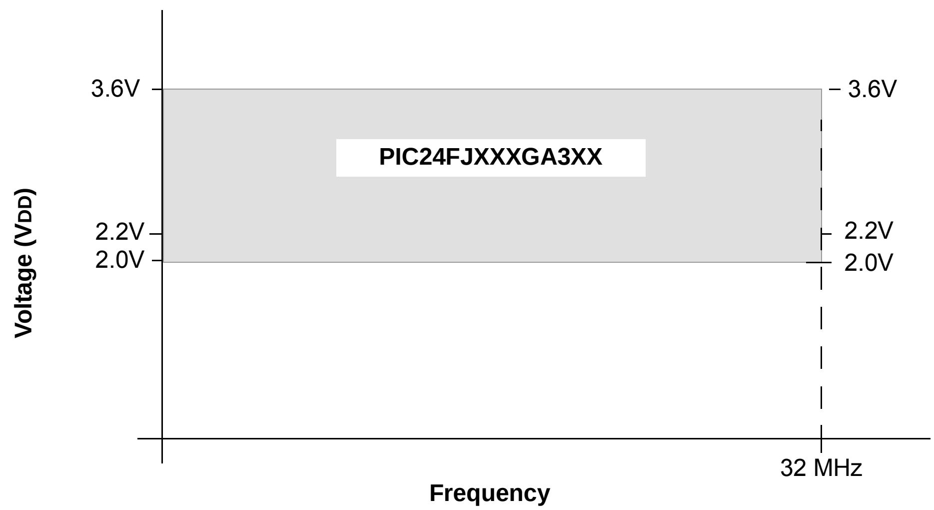
bit 4-0 **DSWDPS<4:0>:** Deep Sleep Watchdog Timer Postscaler Select bits

11111 = 1:68,719,476,736 (25.7 days)
11110 = 1:34,359,738,368(12.8 days)
11101 = 1:17,179,869,184 (6.4 days)
11100 = 1:8,589,934592 (77.0 hours)
11011 = 1:4,294,967,296 (38.5 hours)
11010 = 1:2,147,483,648 (19.2 hours)
11001 = 1:1,073,741,824 (9.6 hours)
11000 = 1:536,870,912 (4.8 hours)
10111 = 1:268,435,456 (2.4 hours)
10110 = 1:134,217,728 (72.2 minutes)
10101 = 1:67,108,864 (36.1 minutes)
10100 = 1:33,554,432 (18.0 minutes)
10011 = 1:16,777,216 (9.0 minutes)
10010 = 1:8,388,608 (4.5 minutes)
10001 = 1:4,194,304 (135.3 s)
10000 = 1:2,097,152 (67.7 s)
01111 = 1:1,048,576 (33.825 s)
01110 = 1:524,288 (16.912 s)
01101 = 1:262,114 (8.456 s)
01100 = 1:131,072 (4.228 s)
01011 = 1:65,536 (2.114 s)
01010 = 1:32,768 (1.057 s)
01001 = 1:16,384 (528.5 ms)
01000 = 1:8,192 (264.3 ms)
00111 = 1:4,096 (132.1 ms)
00110 = 1:2,048 (66.1 ms)
00101 = 1:1,024 (33 ms)
00100 = 1:512 (16.5 ms)
00011 = 1:256 (8.3 ms)
00010 = 1:128 (4.1 ms)
00001 = 1:64 (2.1 ms)
00000 = 1:32 (1 ms)

NOTES:

32.1 DC Characteristics

FIGURE 32-1: PIC24FJ128GA310 FAMILY VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



Note: VCAP (nominal On-Chip Regulator output voltage) = 1.8V.

TABLE 32-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
PIC24FJ128GA310 Family:					
Operating Junction Temperature Range	T_J	-40	—	+125	°C
Operating Ambient Temperature Range	T_A	-40	—	+85	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_{JMAX} - T_A)/\theta_{JA}$			W

TABLE 32-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Note
Package Thermal Resistance, 14x14x1 mm 100-pin TQFP	θ_{JA}	43.0	—	°C/W	**(Note 1)**
Package Thermal Resistance, 12x12x1 mm 100-pin TQFP	θ_{JA}	45.0	—	°C/W	**(Note 1)**
Package Thermal Resistance, 12x12x1 mm 80-pin TQFP	θ_{JA}	48.0	—	°C/W	**(Note 1)**
Package Thermal Resistance, 10x10x1 mm 64-pin TQFP	θ_{JA}	48.3	—	°C/W	**(Note 1)**
Package Thermal Resistance, 9x9x0.9 mm 64-pin QFN	θ_{JA}	28.0	—	°C/W	**(Note 1)**
Package Thermal Resistance, 10x10x1.1 mm 121-pin BGA	θ_{JA}	40.2	—	°C/W	**(Note 1)**

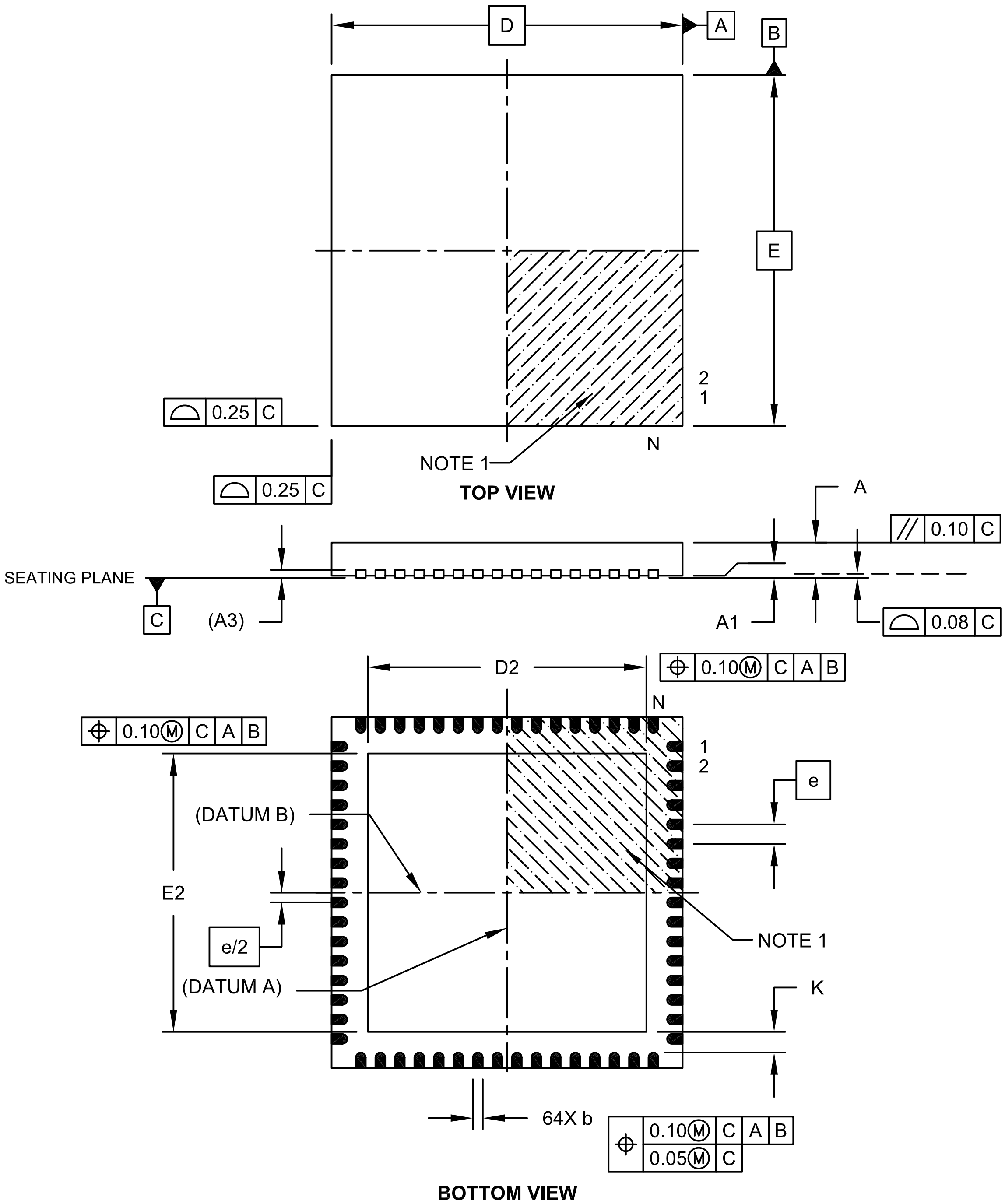
Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

33.3 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-149C Sheet 1 of 2